

Docket No. 251496US40RE

IN RE APPLICATION OF: Motoo ASAI, et al.

SERIAL NO: 10/829,479

FILED: April 22, 2004

FOR: MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD, AND RESIN COMPOSITION FOR FILLING THROUGH-HOLE



BP

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Transmitted herewith is an amendment in the above-identified application.

☐ No additional fee is required

☐ Small entity status of this application under 37 C.F.R. §1.9 and §1.27 is claimed.

☒ Additional documents filed herewith: Request for Extension of Time (2 months); Terminal Disclaimer; Filing Receipt of 7/26/2004 (copy); Consent of Assignee filed 7/26/2004 (copy); Statement under 37 CFR §3.73(b) filed 7/26/2004 (copy); Assignment filed 7/26/2004 (copy); Letter; Japanese Office Action

The Fee has been calculated as shown below:

| CLAIMS | CLAIMS REMAINING | | HIGHEST NUMBER PREVIOUSLY PAID | NO. EXTRA CLAIMS | RATE | CALCULATIONS |
|------------------|------------------|--|--------------------------------|------------------------------|-----------|--------------|
| TOTAL | 98 | MINUS | 92 | 6 | x \$50 = | \$300.00 |
| INDEPENDENT | 13 | MINUS | 14 | 0 | x \$200 = | \$0.00 |
| APPLICATION SIZE | | MINUS | 100 | 0 (each addtl. 50 sheets) | x \$250 = | \$0.00 |
| | | <input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS | | | + \$360 = | \$0.00 |
| | | TOTAL OF ABOVE CALCULATIONS | | | | \$300.00 |
| | | <input type="checkbox"/> Reduction by 50% for filing by Small Entity | | | | \$0.00 |
| | | TOTAL | | | | \$300.00 |

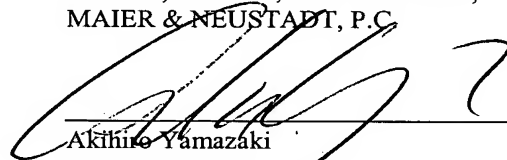
☐ A check in the amount of \$0.00 is attached.

☒ Credit card payment form is attached to cover the fees in the amount of \$880.00.

☒ Please charge any additional Fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

☒ If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136, and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.


Akihiko Yamazaki
Registration No. 46,155

Customer Number

22850

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSMMN 05/03)



DOCKET NO.: 251496US40RE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Motoo ASAI, et al.

SERIAL NO: 10/829,479

GROUP: 1775

FILED: April 22, 2004

EXAMINER: LAM, CATHY F.F.

FOR: MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING
METHOD, AND RESIN COMPOSITION FOR FILLING THROUGH-HOLE

LETTER

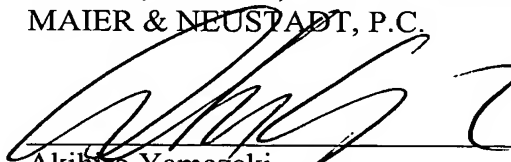
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Submitted herewith is a Japanese Office Action for the Examiner's consideration. The reference(s) cited therein have been previously filed on April 3, 2007.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.


Akihito Yamazaki
Registration No. 46,155

Customer Number

22850

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSMMN 03/06)

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(TRANSLATION)

Reference No.:14-133

Mailing No.:164714

Mailing Date: April 10, 2007

NOTICE OF GROUND FOR REJECTION

Re: Patent Application No.2002-245241

Drafting Date: April 3, 2007

From: KUROIWA Takashi, Examiner of Patent Office 9527 3S00

To: Junzo OGAWA, Representative for Applicant of Patent (and one other)

Applied clauses: Section 29(2)

This application is deemed to be rejected on the following grounds. If the applicant has any objection against this, an argument must be filed within 60 days.

GROUND

The inventions relating to the claims below of this application are the inventions disclosed in the paper publications distributed below or the inventions made available to the public through the telecommunication line in Japan or in the foreign countries prior to the filing date of this application, and the present application cannot be allowed by virtue of the provisions of Sec.29 (2) of Patent Law:

REMARKS (see the list of cited references)

- Claim 1-5
- Cited reference 1
- Remarks

The inventions disclosed in Claim 1-5 of this divisional application are exactly same as those in Claim 1-5 of the application of JP 10-67064, which was filed prior to this divisional application, and therefore the filing of this divisional application will not be allowed.

LIST OF REFERENCES

1. JP-A-11-266082

RECORD OF SEARCH RESULT FOR PRIOR ART REFERENCES

- Field in which a search was conducted: IPC H05K 3/46

This record of search result for prior art references does not constitute grounds for rejection.

Please contact below if you have any inquiry or wish for interview regarding the content of notice of ground for rejection.

Division for Transporting and Setting-Up (Setting-Up and Manufacturing) in Second
Department of Patent Examination
Telephone No.: 03(3581)1101 (x3389)

拒絶理由通知書

| | |
|----------|-----------------|
| 特許出願の番号 | 特願2002-245241 |
| 起案日 | 平成19年 4月 3日 |
| 特許庁審査官 | 黒石 孝志 9527 3S00 |
| 特許出願人代理人 | 小川 順三(外 1名) 様 |
| 適用条文 | 第29条第1項 |

この出願は、次の理由によって拒絶をすべきものである。これについて意見があれば、この通知書の発送の日から60日以内に意見書を提出して下さい。

理 由

この出願の下記の請求項に係る発明は、その出願前に日本国内又は外国において、頒布された下記の刊行物に記載された発明又は電気通信回線を通じて公衆に利用可能となった発明であるから、特許法第29条第1項第3号に該当し、特許を受けることができない。

記 (引用文献等については引用文献等一覧参照)

- ・請求項 1-5
- ・引用文献等 1
- ・備考 本願の請求項1-5に係る発明は、分割前の特願平10-67064号の請求項1-5に係る発明と同一であることから、分割出願は認められない。

引 用 文 献 等 一 覧

1. 特開平11-266082号公報

先行技術文献調査結果の記録

- ・調査した分野 I P C H05K 3/46

この先行技術文献調査結果の記録は拒絶理由を構成するものではありません。

この拒絶理由通知の内容に関するお問い合わせ、または面接のご希望がございましたら下記までご連絡下さい。

特許審査第二部 搬送組立 TEL 03 (3581) 1101 内線3389



OSMM&N File No. 251496US90RE

Dept.: E/M

By: MM/jmo

✓ Serial No. 10/829,479

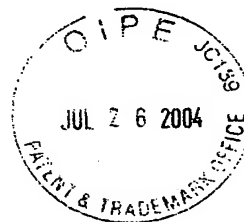
In the matter of the Application of: Motoo ASAI, et al.

For: MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD, AND RESIN COMPOSITION FOR FILLING THROUGH-HOLE

Due Date: August 14, 2004

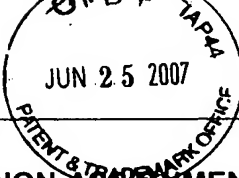
The following has been received in the U.S. Patent Office on the date stamped hereon:

- Dep. Acct. Order Form
- Cover Letter
- Notice to File Missing Parts
- Response to Notice to File Missing Parts of Reissue Application
- Reissue Application Declaration (3 pages) w/ a copy of the specification attached (32 pages)
- Consent of Assignee (1 page)
- Statement under 37 CFR 3.73(b) (1page) w/ a copy of an assignment from the Inventors of the Patent No. 6,376,049 B1 attached (3 pages)



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COPY



**REISSUE APPLICATION:
CONSENT OF ASSIGNEE; STATEMENT OF NON-ASSIGNMENT**

Docket Number
251496US90RE

This is part of the application for a reissue patent based on the original patent identified below.

Name of Patentee(s)
Motoo ASAI, et al.

Patent Number
6,376,049 B1

Date Patent Issued
April 23, 2002

Title of Invention
MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD, AND RESIN
COMPOSITION FOR FILLING THROUGH-HOLE

One box must
be checked

☒ Filed herein is a statement under 37 CFR 3.73(b).

☐ Ownership of the patent is in the inventor(s), and no assignment of the patent has been made.

The written consent of all assignees owning an undivided interest in the original patent is included in this application for reissue.

Signature

Yoshifumi IWATA

Date

5/26/2004

Typed or printed name of person signing for assignee

Yoshifumi IWATA

The assignee(s) owning an undivided interest in said original patent is/are: Ibiden Co., Ltd.
and the assignee(s) consents to the accompanying application for reissue.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine and imprisonment, or both, under 18 U.S.C. 1001, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this declaration is directed.

Name of assignee/inventor (if not assigned)

Signature of person signing for assignee

Date

Typed or printed name of person signing for assignee (if assigned)

COPY



STATEMENT UNDER 37 CFR 3.73(b)

Applicant/Patent Owner: Motoo ASAI, et al.

Application No./Patent No.: 6,376,049 B1 Filed/Issue Date: April 23, 2002

Entitled: MULTILAYER PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD, AND RESIN COMPOSITION FOR FILLING THROUGH-HOLE

Ibiden Co., Ltd., a Corporation

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, government agency, etc.)

States that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of less than the entire right, title and interest.

The extent (by, percentage) of its ownership interest is _____ %

in the patent application/patent identified above by virtue of either:

- A. ☒ An assignment from the inventor(s) of the patent application/patent identified above. The assignment was recorded in the United States Patent and Trademark Office at Reel 010176/0334, Frame 0334, or for which a copy thereof is attached.

OR

- B. ☐ A chain of title from the inventor(s), of the patent application/patent identified above, to the current assignee as shown below:

1. From: _____ To: _____

The document was recorded in the United States Patent and Trademark Office at Reel _____, Frame _____, or for which a copy thereof is attached.

2. From: _____ To: _____

The document was recorded in the United States Patent and Trademark Office at Reel _____, or for which a copy thereof is attached.

3. From: _____ To: _____

The document was recorded in the United States Patent and Trademark Office at Reel _____, or for which a copy thereof is attached.

☐ Additional documents in the chain of title are listed on a supplemental sheet.

- ☒ Copies of assignments or other documents in the chain of title are attached.

[NOTE: A separate copy (i.e., the original assignment document or a true copy of the original document) must be submitted to Assignment Division in accordance with 37 CFR Part 3, if the assignment is to be recorded in the records of the USPTO. See MPEP 302.08]

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

5/26/2004

Date

Yoshifumi IWATA

Typed or printed name

Yoshifumi Iwata

Signature

President

Title

COPY

ASSIGNMENT

WHEREAS, **Motoo ASAI**, a citizen of Japan, whose post office address is c/o IBIDEN Co., Ltd., 1-1, Kitakata, Ibigawa-cho, Ibi-gun, Gifu 501-0601, Japan, **Kenichi SHIMADA**, a citizen of Japan, whose post office address is c/o IBIDEN Co., Ltd., 1-1, Kitakata, Ibigawa-cho, Ibi-gun, Gifu 501-0601, Japan, **Kouta NODA**, a citizen of Japan, whose post office address is c/o IBIDEN Co., Ltd., 1-1, Kitakata, Ibigawa-cho, Ibi-gun, Gifu 501-0601 Japan, **Takashi KARIYA**, a citizen of Japan, whose post office address is c/o IBIDEN Co., Ltd., 1-1, Kitakata, Ibigawa-cho, Ibi-gun, Gifu 501-0601, Japan, and **Hiroshi SEGAWA**, a citizen of Japan, whose post office address is c/o IBIDEN Co., Ltd., 1-1, Kitakata, Ibigawa-cho, Ibi-gun, Gifu 501-0601, Japan, hereinafter referred to as the ASSIGNORS, have invented a certain improvement relating to

MULTILAYER PRINTED WIRING BOARD AND ITS PRODUCTION
PROCESS, RESIN COMPOSITION FOR FILLING THROUGH-HOLE

for which they have, on the dates indicated below, executed an application for Letters Patent of the United States to be filed in the United States Patent and Trademark Office, which is a National Stage Application of International Application No. PCT/JP98/04584, filed October 12, 1998.

AND WHEREAS, IBIDEN Co., Ltd., a corporation organized and existing under the laws of Japan, whose post-office address is 1, Kanda-cho 2-chome, Ogaki-shi, Gifu 503-0917, Japan, hereinafter known as the ASSIGNEE, is desirous of acquiring the entire right, title and interest for the United States in and to said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues, and prolongations thereof.

NOW, THIS WITNESSETH that for and in consideration of One Dollar (\$1.00) and other good and valuable consideration, the receipt whereof is hereby acknowledged, said ASSIGNORS hereby assign, sell and transfer to said ASSIGNEE, its assigns and legal representatives, the entire and exclusive right, title and interest in and to said invention and application, for the United States including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted therefor, said ASSIGNEE and its assigns and legal representatives to have, hold, exercise and enjoy the said invention and application, including any and all divisions and continuations thereof, and any and all Letters Patent which may be granted thereon, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges, and advantages in any ways arising from or pertaining thereto, for and during the term or terms of any and all such Letters Patent when granted, including any and all renewals, reissues, and prolongations thereof, for the use and benefit of said ASSIGNEE and its assigns and legal representatives in as ample and beneficial a manner to all intents and purposes as the said ASSIGNORS might or could have held and enjoyed the same, if this assignment had not been made.

AND said ASSIGNORS hereby agree to execute all papers necessary to file applications in the United States for said invention and to assign the same to said ASSIGNEE, or any assignee

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acquiring title to said invention, and to execute any other papers that may be needed in connection with filing said application and securing Letters Patent thereon.

AND said ASSIGNORS authorize and request the Commissioner of Patents to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said ASSIGNEE, its assigns and legal representatives, in accordance herewith.

IN TESTIMONY WHEREOF, this assignment is executed by said ASSIGNORS, on the respective dates indicated below.

Witnessed by:

Tsunehiro Kohara 02/July/99
Name Date
Tsunehiro KOHARA

Motoo Asai 01/July/99
Motoo ASAI Date

Tomohiro Nishikawa 02/July/99
Name Date
Tomohiro NISHIKAWA

Witnessed by:

Tsunehiro Kohara 02/July/99
Name Date
Tsunehiro KOHARA

Ken-ichi Shimada 01/July/99
Kenichi SHIMADA Date

Tomohiro Nishikawa 02/July/99
Name Date
Tomohiro NISHIKAWA

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Witnessed by:

Tsunehiro Kohara 02/July/99
Name Date
Tsunehiro KOHARA

Kouta Noda 01/July/99
Date
Kouta NODA

Tomohiro Nishikawa 02/July/99
Name Date
Tomohiro NISHIKAWA

Witnessed by:

Tsunehiro Kohara 02/July/99
Name Date
Tsunehiro KOHARA

Takashi Kariya 01/July/99
Date
Takashi KARIYA

Tomohiro Nishikawa 02/July/99
Name Date
Tomohiro NISHIKAWA

Witnessed by:

Tsunehiro Kohara 02/July/99
Name Date
Tsunehiro KOHARA

Hiroshi Segawa 01/July/99
Date
Hiroshi SEGAWA

Tomohiro Nishikawa 02/July/99
Name Date
Tomohiro NISHIKAWA

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